

austriamicrosystems AG
A 8141 Schloss Premstätten, Austria

T. +43 (0) 3136 500-5437
F. +43 (0) 3136 500-5361
herwig.klimesch@austriamicrosystems.com
www.austriamicrosystems.com

Unterpremstätten, 22. Nov. 2010

Product Change Notification PCN 06-2010

Change of Bill of Material

Dear Customer,

austriamicrosystems AG is pleased to inform you that our Assembly Partner, Carsem, Inc., located in 30720 Ipoh, Malaysia, is changing the **leadframe from the existing matrix tooling to the high density tooling, the Epoxy Type and the Mold Compound Type** of the aforementioned affected austriamicrosystems device/product.

Changes will be:

MLP(X) package:

- From a "Standard Leadframe Matrix" to a "High Density Matrix."
- From "Sumikon EME 7730LF Mold Compound" to "SumikonG770HC Mold Compound."

MSOP package:

- From a "Standard Leadframe Matrix" to a "High Density Matrix."
- From "Ablebond 84-1LMISR 4 Epoxy" to "Henkel QMI519 Epoxy"
- From "Sumikon EME 6600 Series Mold Compound" to "Hitachi CEL 8240HF10LXC Mold Compound."

QSOP package:

- From a "Standard Leadframe Matrix" to a "High Density Matrix."
- From "Ablebond 84-1LMISR 4 Epoxy" to "Henkel QMI519 Epoxy"
- From "Sumikon G600 Mold Compound" to "Hitachi CEL 8240HF10LXC Mold Compound."

SC 70 package:

- From a “Standard Leadframe Matrix” to a “High Density Matrix.”
- From “Nitto MP 8000C Mold Compound” to “Hitachi CEL 8240HF10LXC Mold Compound.”
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SOIC package:

- From a “Standard Leadframe Matrix” to a “High Density Matrix.”
- From “Ablebond 84-1LMISR 4 Epoxy” to “Henkel QMI519 Epoxy”
- From “Sumikon EME 6600 Series Mold Compound” to “Hitachi CEL 8240HF10LXC Mold Compound.”

SOT 23 and TSOT 23 package:

- From a “Standard Leadframe Matrix” to a “High Density Matrix.”
- From “Hitachi CEL-9220 HF 13 Mold Compound” to “Hitachi CEL 8240HF10LXC Mold Compound.”

These changes were initiated by our assembly partner and are fully supported by austriamicrosystems due to the advantages and benefits over the old materials.

Purpose of Change:

The change in leadframe is expected to increase and improve the factory’s capacity that eventually will impact the factory’s delivery performance.

With regard to the epoxy and moldcompound type change, this is in-line with austriamicrosystems AG’s general direction of moving to RoHS/green materials on its’ present and future products. Additionally the new material set was selected for its superior thermomechanical properties and low moisture absorption.

Set of package related qualification tests:

austriamicrosystems currently qualifies the new material set based on the following tests in order to determine that the technology is capable of passing the specified quality requirements.

- Temperature Cycling Test
- HAST
- Autoclave Test

Impact on Product:

No impact on product is anticipated, as complete reliability testing both at Carsem and austriamicrosystems will be done to ensure that there will no changes in terms of form, fit, function and reliability of the device.

Affected products:

Please refer to separate mail (subject: "PCN06-2010_product list")

Date of Implementation: January 2011

A detailed Qualification Report will be available upon request. We ask for your kind cooperation in supporting this change.

Please be advised that, unless we received your written refusal concerning this PCN in writing within 30 days, the PCN shall be deemed accepted.

If you do have further questions, please do not hesitate to contact me.

Best Regards,

Herwig Klimesch
austriamicrosystems AG
Director of Quality and Environment